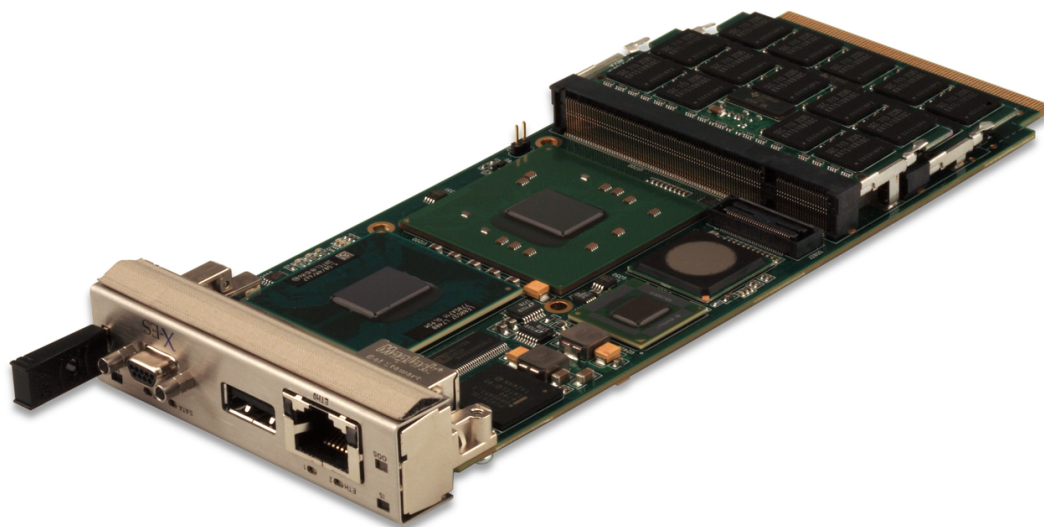


XPedite7040

Intel® Core™ Duo or Intel® Core™2 Duo Processor-Based AMC Module

- ▶ Intel Core Duo or Intel Core 2 Duo processor at up to 1.5 GHz
- ▶ Intel 3100 chipset
- ▶ Front panel Gigabit Ethernet port
- ▶ Front panel RS-232 serial port
- ▶ Front panel USB 2.0 port
- ▶ Complies with AMC.0 and MicroTCA.0 (μTCA)
- ▶ AMC.1 x4 PCI Express interface
- ▶ AMC.2 dual Gigabit Ethernet 1000BASE-BX interfaces
- ▶ AMC.3 dual SATA interfaces
- ▶ Two PC3200 SO-RDIMMs, up to 8 GB
- ▶ 4 GB of NAND flash
- ▶ Up to 4 MB of Firmware Hub (FWH) storage
- ▶ AMI BIOS
- ▶ Linux BSP
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP
- ▶ Green Hills INTEGRITY BSP
- ▶ Microsoft Windows drivers



XPedite7040

The XPedite7040 is a single-width, mid-size or full-size Advanced Mezzanine Card (AMC) single board computer designed to provide maximum performance and I/O options while minimizing power consumption. The Ultra Low Voltage (ULV) Intel Core Duo processor or Low Voltage (LV) Intel Core 2 Duo processor provides the XPedite7040 with a significant performance-per-watt processing advantage. Additionally, the Intel 3100 chipset combines the functionality of an integrated server-class memory controller (Northbridge) and an I/O controller (Southbridge) into a single device that is specifically intended for power- and board-space-sensitive embedded applications.

The XPedite7040 can be installed in an AdvancedTCA (ATCA) AMC.0-compliant carrier or a MicroTCA.0 (μTCA)-compliant backplane. The XPedite7040 supports an AMC.1 x4 PCI Express interface, dual AMC.2 Gigabit Ethernet 1000BASE-BX interfaces, and dual AMC.3 SATA interfaces. Additional serial and GPIO is provided through the backplane connector.

The XPedite7040 supports two PC3200 SO-RDIMM modules and 4 GB of NAND flash for ample on-card memory capacity. 4 MB of Firmware Hub (FWH) space is also supported for redundant BIOS or OS kernel storage.

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Processor

- Intel Core Duo or Intel Core 2 Duo processor
- Up to 1.5 GHz
- Up to 4 MB L2 cache
- Up to 166 MHz (667 MT/s) FSB

Memory and I/O Controller Hub

- Intel 3100
- DDR2-400 ECC SDRAM
- 4 GB of NAND flash
- 4 MB of Firmware Hub (FWH) storage

AMC Backplane Interconnect

- Complies with AMC.0 and MicroTCA.0 (µTCA)
- AMC.1 x4 PCI Express interface
- AMC.2 dual Gigabit Ethernet 1000BASE-BX interfaces
- AMC.3 dual SATA interfaces
- Dual USB 2.0 interfaces
- RS-232/RS-422 serial interface

Front Panel I/O

- Micro DB-9, RS-232 serial port
- USB 2.0 port
- 10/100/1000BASE-T Gigabit Ethernet port

Software

- AMI BIOS
- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Power Requirements

Tested at 25°C ambient with 2 GB DDR2 and 1.2-GHz CPU

- Less than 30 Watts

Supported Ruggedization Level	Level 1
Cooling Method	Standard Air-Cooled
Operating Temperature	0 to +55 °C ambient (300 LFM)
Storage Temperature	0 to +85 °C ambient
Vibration	0.002 g ² /Hz, 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing

